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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

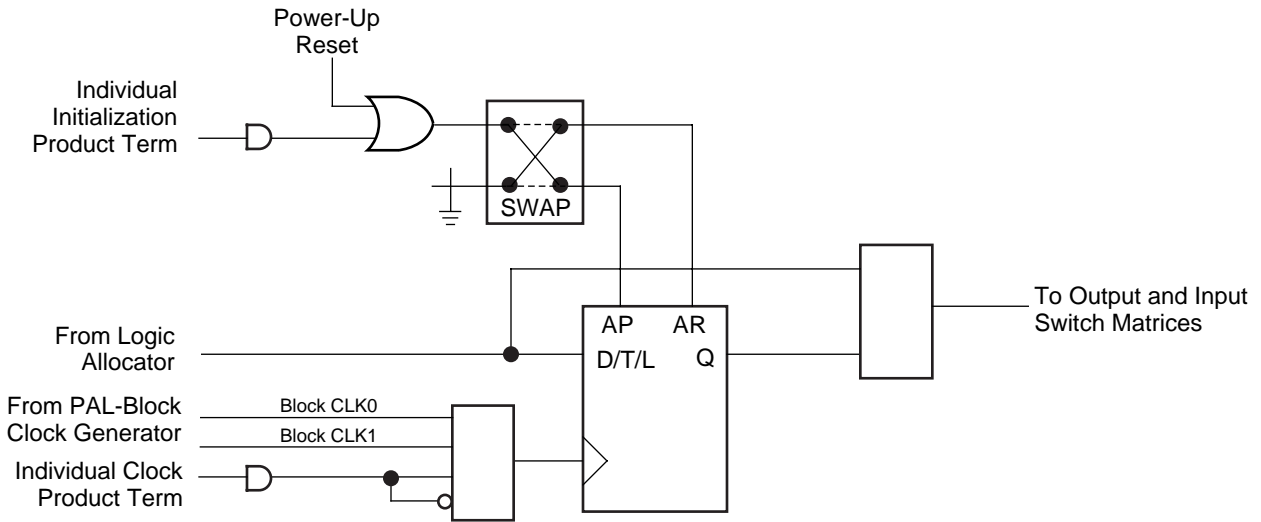
Product Status	Not For New Designs
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	-
Number of Macrocells	64
Number of Gates	-
Number of I/O	64
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/m4a3-64-64-7vni

Macrocell

The macrocell consists of a storage element, routing resources, a clock multiplexer, and initialization control. The macrocell has two fundamental modes: synchronous and asynchronous (Figure 5). The mode chosen only affects clocking and initialization in the macrocell.



a. Synchronous mode



b. Asynchronous mode

17466G-010

Figure 5. Macrocell

In either mode, a combinatorial path can be used. For combinatorial logic, the synchronous mode will generally be used, since it provides more product terms in the allocator.

Table 8. Register/Latch Operation

Configuration	Input(s)	CLK/LE ¹	Q+
D-type Register	D=X	0, 1, ↓ (↑)	Q
	D=0	↑ (↓)	0
	D=1	↑ (↓)	1
T-type Register	T=X	0, 1, ↓ (↑)	Q
	T=0	↑ (↓)	Q
	T=1	↑ (↓)	\bar{Q}
D-type Latch	D=X	1 (0)	Q
	D=0	0 (1)	0
	D=1	0 (1)	1

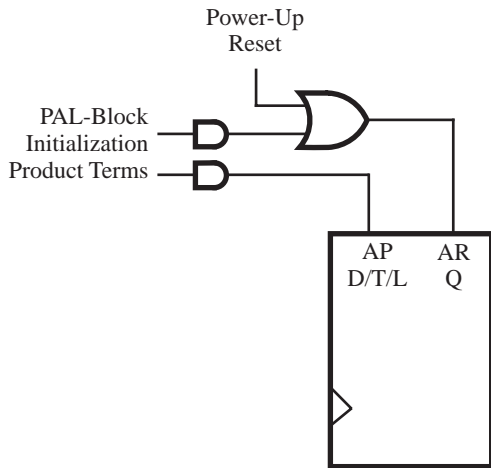
Note:

1. Polarity of CLK/LE can be programmed

Although the macrocell shows only one input to the register, the XOR gate in the logic allocator allows the D-, T-type register to emulate J-K, and S-R behavior. In this case, the available product terms are divided between J and K (or S and R). When configured as J-K, S-R, or T-type, the extra product term must be used on the XOR gate input for flip-flop emulation. In any register type, the polarity of the inputs can be programmed.

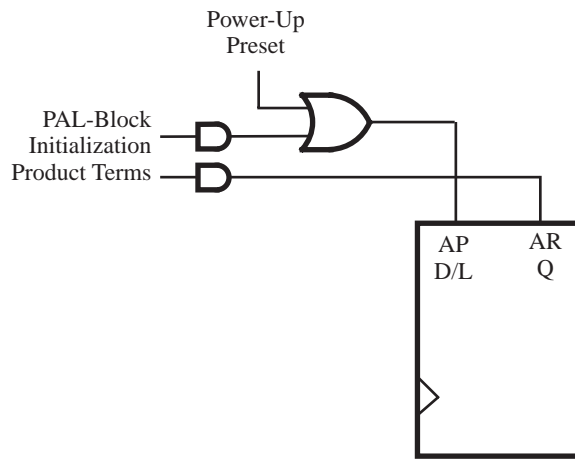
The clock input to the flip-flop can select any of the four PAL block clocks in synchronous mode, with the additional choice of either polarity of an individual product term clock in the asynchronous mode.

The initialization circuit depends on the mode. In synchronous mode (Figure 7), asynchronous reset and preset are provided, each driven by a product term common to the entire PAL block.



a. Power-up reset

17466G-012



b. Power-up preset

17466G-013

Figure 7. Synchronous Mode Initialization Configurations

Table 10. Output Switch Matrix Combinations for ispMACH 4A Devices with 2:1 Macrocell-I/O Cell Ratio

Macrocell	Routable to I/O Cells
M12, M13	I/03, I/04, I/05, I/06
M14, M15	I/04, I/05, I/06, I/07

I/O Cell	Available Macrocells
I/00	M0, M1, M2, M3, M4, M5, M6, M7
I/01	M2, M3, M4, M5, M6, M7, M8, M9
I/02	M4, M5, M6, M7, M8, M9, M10, M11
I/03	M6, M7, M8, M9, M10, M11, M12, M13
I/04	M8, M9, M10, M11, M12, M13, M14, M15
I/05	M0, M1, M10, M11, M12, M13, M14, M15
I/06	M0, M1, M2, M3, M12, M13, M14, M15
I/07	M0, M1, M2, M3, M4, M5, M14, M15

Table 11. Output Switch Matrix Combinations for M4A3-256/160 and M4A3-256/192

Macrocell	Routable to I/O Cells							
M0	I/00	I/01	I/02	I/03	I/04	I/05	I/06	I/07
M1	I/00	I/01	I/02	I/03	I/04	I/05	I/06	I/07
M2	I/00	I/01	I/02	I/03	I/04	I/05	I/06	I/07
M3	I/00	I/01	I/02	I/03	I/04	I/05	I/06	I/07
M4	I/00	I/01	I/02	I/03	I/04	I/05	I/06	I/07
M5	I/00	I/01	I/02	I/03	I/04	I/05	I/06	I/07
M6	I/00	I/01	I/02	I/03	I/04	I/05	I/06	I/07
M7	I/00	I/01	I/02	I/03	I/04	I/05	I/06	I/07
M8	I/08	I/09	I/010	I/011	I/012	I/013	I/014	I/015
M9	I/08	I/09	I/010	I/011	I/012	I/013	I/014	I/015
M10	I/08	I/09	I/010	I/011	I/012	I/013	I/014	I/015
M11	I/08	I/09	I/010	I/011	I/012	I/013	I/014	I/015
M12	I/08	I/09	I/010	I/011	I/012	I/013	I/014	I/015
M13	I/08	I/09	I/010	I/011	I/012	I/013	I/014	I/015
M14	I/08	I/09	I/010	I/011	I/012	I/013	I/014	I/015
M15	I/08	I/09	I/010	I/011	I/012	I/013	I/014	I/015

I/O Cell	Available Macrocells							
I/00	M0	M1	M2	M3	M4	M5	M6	M7
I/01	M0	M1	M2	M3	M4	M5	M6	M7
I/02	M0	M1	M2	M3	M4	M5	M6	M7
I/03	M0	M1	M2	M3	M4	M5	M6	M7
I/04	M0	M1	M2	M3	M4	M5	M6	M7
I/05	M0	M1	M2	M3	M4	M5	M6	M7
I/06	M0	M1	M2	M3	M4	M5	M6	M7
I/07	M0	M1	M2	M3	M4	M5	M6	M7

Table 11. Output Switch Matrix Combinations for M4A3-256/160 and M4A3-256/192

Macrocell	Routable to I/O Cells							
I/O8	M8	M9	M10	M11	M12	M13	M14	M15
I/O9	M8	M9	M10	M11	M12	M13	M14	M15
I/O10	M8	M9	M10	M11	M12	M13	M14	M15
I/O11	M8	M9	M10	M11	M12	M13	M14	M15
I/O12	M8	M9	M10	M11	M12	M13	M14	M15
I/O13	M8	M9	M10	M11	M12	M13	M14	M15
I/O14	M8	M9	M10	M11	M12	M13	M14	M15
I/O15	M8	M9	M10	M11	M12	M13	M14	M15

Table 12. Output Switch Matrix Combinations for M4A(3,5)-32/32

Macrocell	Routable to I/O Cells
M0, M1, M2, M3, M4, M5, M6, M7	I/O0, I/O1, I/O2, I/O3, I/O4, I/O5, I/O6, I/O7
M8, M9, M10, M11, M12, M13, M14, M15	I/O8, I/O9, I/O10, I/O11, I/O12, I/O13, I/O14, I/O15

I/O Cell	Available Macrocells
I/O0, I/O1, I/O2, I/O3, I/O4, I/O5, I/O6, I/O7	M0, M1, M2, M3, M4, M5, M6, M7
I/O8, I/O9, I/O10, I/O11, I/O12, I/O13, I/O14, I/O15	M8, M9, M10, M11, M12, M13, M14, M15

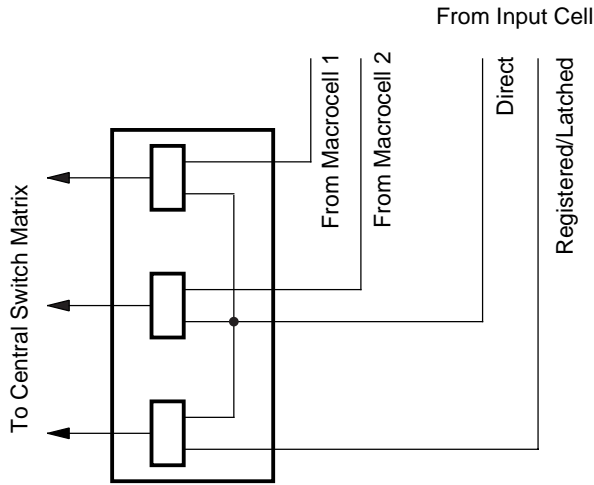
Table 13. Output Switch Matrix Combinations for M4A3-64/64

Macrocell	Routable to I/O Cells
M0, M1	I/O0, I/O1, I/O10, I/O11, I/O12, I/O13, I/O14, I/O15
M2, M3	I/O0, I/O1, I/O2, I/O3, I/O12, I/O13, I/O14, I/O15
M4, M5	I/O0, I/O1, I/O2, I/O3, I/O4, I/O5, I/O14, I/O15
M6, M7	I/O0, I/O1, I/O2, I/O3, I/O4, I/O5, I/O6, I/O7
M8, M9	I/O2, I/O3, I/O4, I/O5, I/O6, I/O7, I/O8, I/O9
M10, M11	I/O4, I/O5, I/O6, I/O7, I/O8, I/O9, I/O10, I/O11
M12, M13	I/O6, I/O7, I/O8, I/O9, I/O10, I/O11, I/O12, I/O13
M14, M15	I/O8, I/O9, I/O10, I/O11, I/O12, I/O13, I/O14, I/O15

I/O Cell	Available Macrocells
I/O0, I/O1	M0, M1, M2, M3, M4, M5, M6, M7
I/O2, I/O3	M2, M3, M4, M5, M6, M7, M8, M9
I/O4, I/O5	M4, M5, M6, M7, M8, M9, M10, M11
I/O6, I/O7	M6, M7, M8, M9, M10, M11, M12, M13
I/O8, I/O9	M8, M9, M10, M11, M12, M13, M14, M15
I/O10, I/O11	M0, M1, M10, M11, M12, M13, M14, M15
I/O12, I/O13	M0, M1, M2, M3, M12, M13, M14, M15
I/O14, I/O15	M0, M1, M2, M3, M4, M5, M14, M15

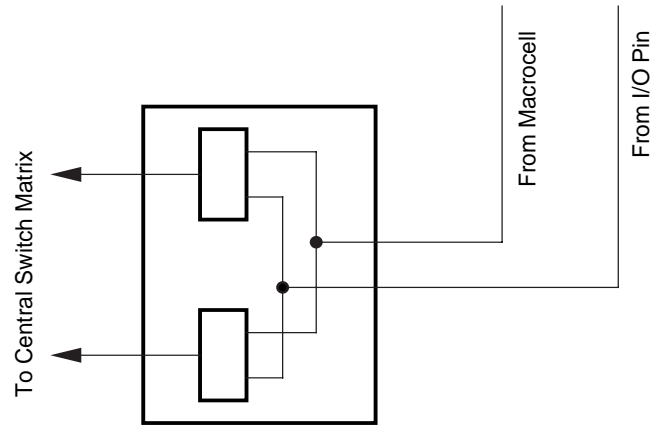
Input Switch Matrix

The input switch matrix (Figures 12 and 13) optimizes routing of inputs to the central switch matrix. Without the input switch matrix, each input and feedback signal has only one way to enter the central switch matrix. The input switch matrix provides additional ways for these signals to enter the central switch matrix.



17466G-002

Figure 12. ispMACH 4A with 2:1 Macrocell-I/O Cell Ratio - Input Switch Matrix

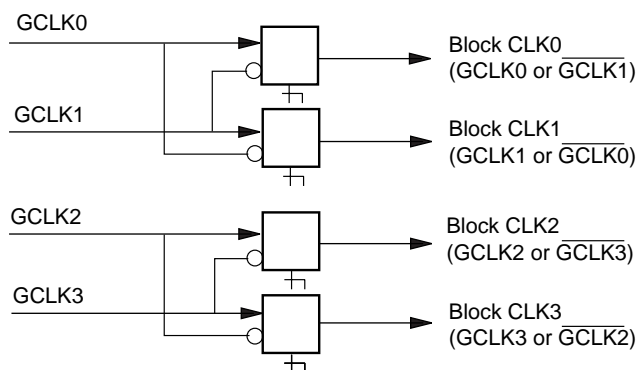


17466G-003

Figure 13. ispMACH 4A with 1:1 Macrocell-I/O Cell Ratio - Input Switch Matrix

PAL Block Clock Generation

Each ispMACH 4A device has four clock pins that can also be used as inputs. These pins drive a clock generator in each PAL block (Figure 14). The clock generator provides four clock signals that can be used anywhere in the PAL block. These four PAL block clock signals can consist of a large number of combinations of the true and complement edges of the global clock signals. Table 14 lists the possible combinations.



17466G-004

Figure 14. PAL Block Clock Generator¹

1. M4A(3,5)-32/32 and M4A(3,5)-64/32 have only two clock pins, GCLK0 and GCLK1. GCLK2 is tied to GCLK0, and GCLK3 is tied to GCLK1.

Table 14. PAL Block Clock Combinations¹

Block CLK0	Block CLK1	Block CLK2	Block CLK3
GCLK0	GCLK1	X	X
$\overline{GCLK1}$	GCLK1	X	X
GCLK0	$\overline{GCLK0}$	X	X
$\overline{GCLK1}$	$\overline{GCLK0}$	X	X
X	X	GCLK2 (GCLK0)	GCLK3 (GCLK1)
X	X	$\overline{GCLK3}$ ($\overline{GCLK1}$)	GCLK3 (GCLK1)
X	X	GCLK2 (GCLK0)	$\overline{GCLK2}$ ($\overline{GCLK0}$)
X	X	$\overline{GCLK3}$ ($\overline{GCLK1}$)	$\overline{GCLK2}$ ($\overline{GCLK0}$)

Note:

1. Values in parentheses are for the M4A(3,5)-32/32 and M4A(3,5)-64/32.

This feature provides high flexibility for partitioning state machines and dual-phase clocks. It also allows latches to be driven with either polarity of latch enable, and in a master-slave configuration.

IEEE 1149.1-COMPLIANT BOUNDARY SCAN TESTABILITY

All ispMACH 4A devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for more complete board-level testing.

IEEE 1149.1-COMPLIANT IN-SYSTEM PROGRAMMING

Programming devices in-system provides a number of significant benefits including: rapid prototyping, lower inventory levels, higher quality, and the ability to make in-field modifications. All ispMACH 4A devices provide In-System Programming (ISP) capability through their Boundary ScanTest Access Ports. This capability has been implemented in a manner that ensures that the port remains compliant to the IEEE 1149.1 standard. By using IEEE 1149.1 as the communication interface through which ISP is achieved, customers get the benefit of a standard, well-defined interface.

ispMACH 4A devices can be programmed across the commercial temperature and voltage range. The PC-based ispVM™ software facilitates in-system programming of ispMACH 4A devices. ispVM takes the JEDEC file output produced by the design implementation software, along with information about the JTAG chain, and creates a set of vectors that are used to drive the JTAG chain. ispVM software can use these vectors to drive a JTAG chain via the parallel port of a PC. Alternatively, ispVM software can output files in formats understood by common automated test equipment. This equipment can then be used to program ispMACH 4A devices during the testing of a circuit board.

PCI COMPLIANT

ispMACH 4A devices in the -5/-55/-6/-65/-7/-10/-12 speed grades are compliant with the *PCI Local Bus Specification* version 2.1, published by the PCI Special Interest Group (SIG). The 5-V devices are fully PCI-compliant. The 3.3-V devices are mostly compliant but do not meet the PCI condition to clamp the inputs as they rise above V_{CC} because of their 5-V input tolerant feature.

SAFE FOR MIXED SUPPLY VOLTAGE SYSTEM DESIGNS

Both the 3.3-V and 5-V V_{CC} ispMACH 4A devices are safe for mixed supply voltage system designs. The 5-V devices will not overdrive 3.3-V devices above the output voltage of 3.3 V, while they accept inputs from other 3.3-V devices. The 3.3-V device will accept inputs up to 5.5 V. Both the 5-V and 3.3-V versions have the same high-speed performance and provide easy-to-use mixed-voltage design capability.

PULL UP OR BUS-FRIENDLY INPUTS AND I/Os

All ispMACH 4A devices have inputs and I/Os which feature the Bus-Friendly circuitry incorporating two inverters in series which loop back to the input. This double inversion weakly holds the input at its last driven logic state. While it is good design practice to tie unused pins to a known state, the Bus-Friendly input structure pulls pins away from the input threshold voltage where noise can cause high-frequency switching. At power-up, the Bus-Friendly latches are reset to a logic level "1." For the circuit diagram, please refer to the document entitled *MACH Endurance Characteristics* on the Lattice Data Book CD-ROM or Lattice web site.

All ispMACH 4A devices have a programmable bit that configures all inputs and I/Os with either pull-up or Bus-Friendly characteristics. If the device is configured in pull-up mode, all inputs and I/O pins are

weakly pulled up. For the circuit diagram, please refer to the document entitled *MACH Endurance Characteristics* on the Lattice Data Book CD-ROM or Lattice web site.

POWER MANAGEMENT

Each individual PAL block in ispMACH 4A devices features a programmable low-power mode, which results in power savings of up to 50%. The signal speed paths in the low-power PAL block will be slower than those in the non-low-power PAL block. This feature allows speed critical paths to run at maximum frequency while the rest of the signal paths operate in the low-power mode.

PROGRAMMABLE SLEW RATE

Each ispMACH 4A device I/O has an individually programmable output slew rate control bit. Each output can be individually configured for the higher speed transition (3 V/ns) or for the lower noise transition (1 V/ns). For high-speed designs with long, unterminated traces, the slow-slew rate will introduce fewer reflections, less noise, and keep ground bounce to a minimum. For designs with short traces or well terminated lines, the fast slew rate can be used to achieve the highest speed. The slew rate is adjusted independent of power.

POWER-UP RESET/SET

All flip-flops power up to a known state for predictable system initialization. If a macrocell is configured to SET on a signal from the control generator, then that macrocell will be SET during device power-up. If a macrocell is configured to RESET on a signal from the control generator or is not configured for set/reset, then that macrocell will RESET on power-up. To guarantee initialization values, the V_{CC} rise must be monotonic, and the clock must be inactive until the reset delay time has elapsed.

SECURITY BIT

A programmable security bit is provided on the ispMACH 4A devices as a deterrent to unauthorized copying of the array configuration patterns. Once programmed, this bit defeats readback of the programmed pattern by a device programmer, securing proprietary designs from competitors. Programming and verification are also defeated by the security bit. The bit can only be reset by erasing the entire device.

HOT SOCKETING

ispMACH 4A devices are well-suited for those applications that require hot socketing capability. Hot socketing a device requires that the device, when powered down, can tolerate active signals on the I/Os and inputs without being damaged. Additionally, it requires that the effects of the powered-down MACH devices be minimal on active signals.

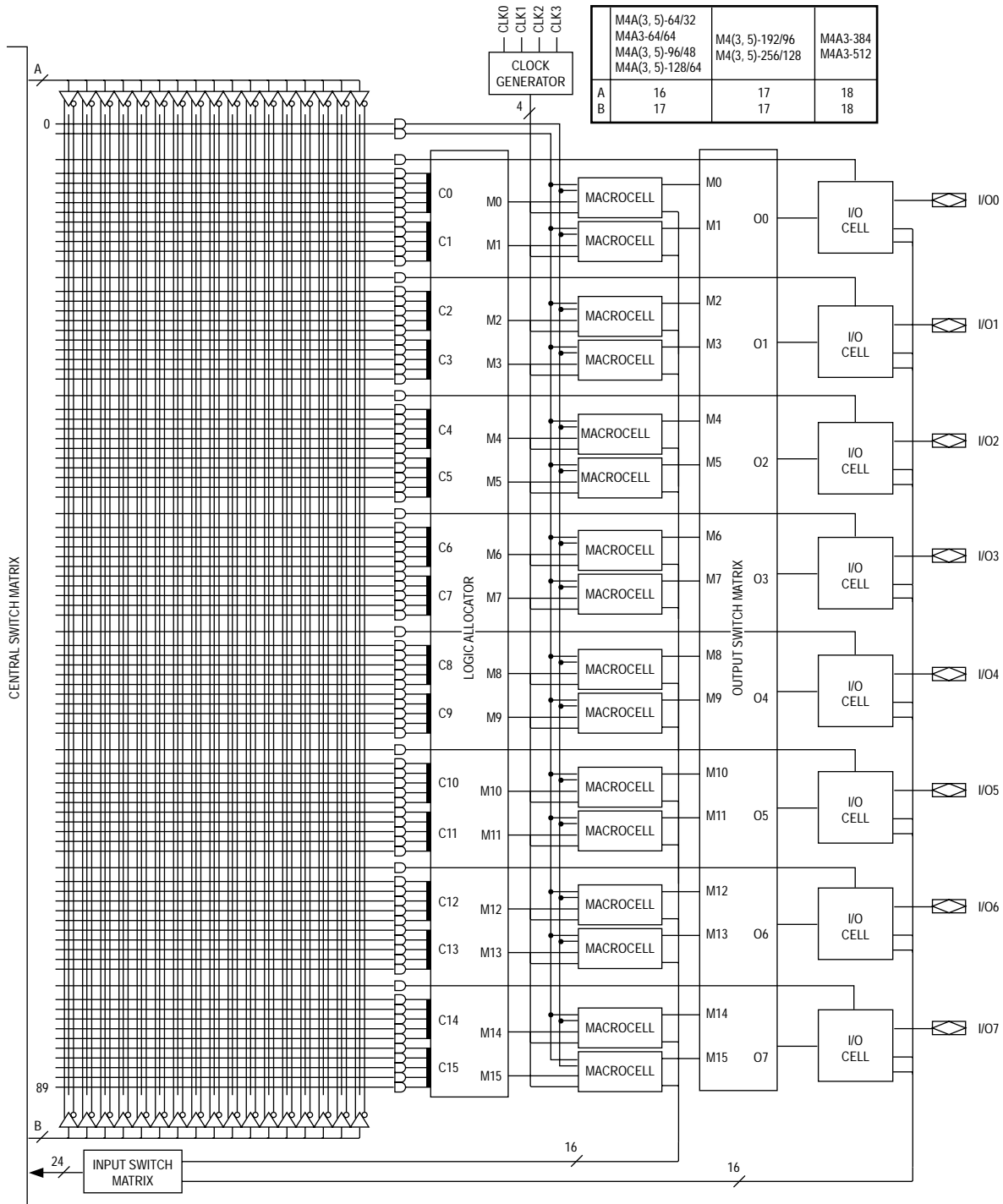


Figure 16. PAL Block for ispMACH 4A with 2:1 Macrocell - I/O Cell Ratio

BLOCK DIAGRAM – M4A(3,5)-64/32



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BLOCK DIAGRAM – M4A3-64/64



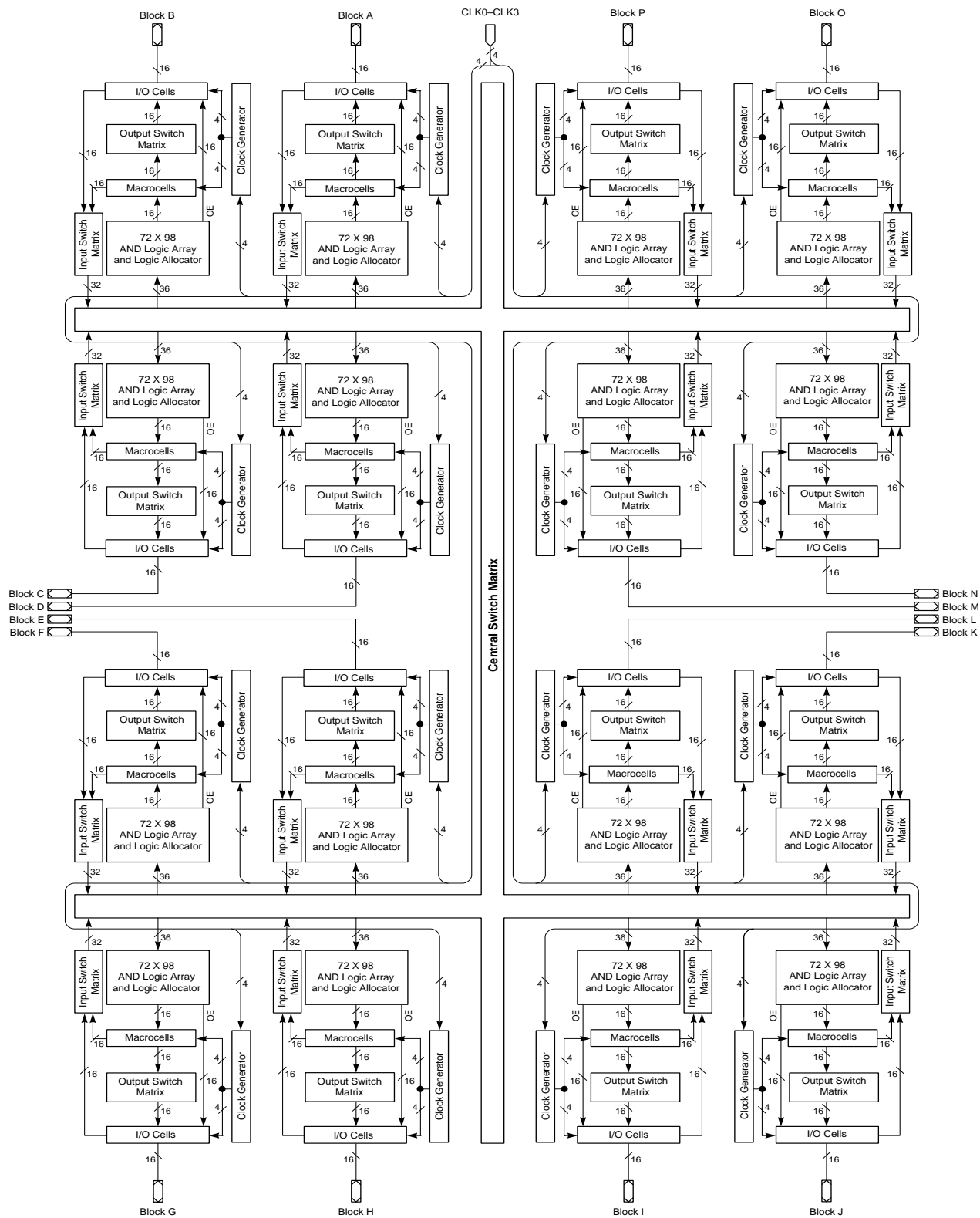
17466H-020A

BLOCK DIAGRAM – M4A(3,5)-96/48



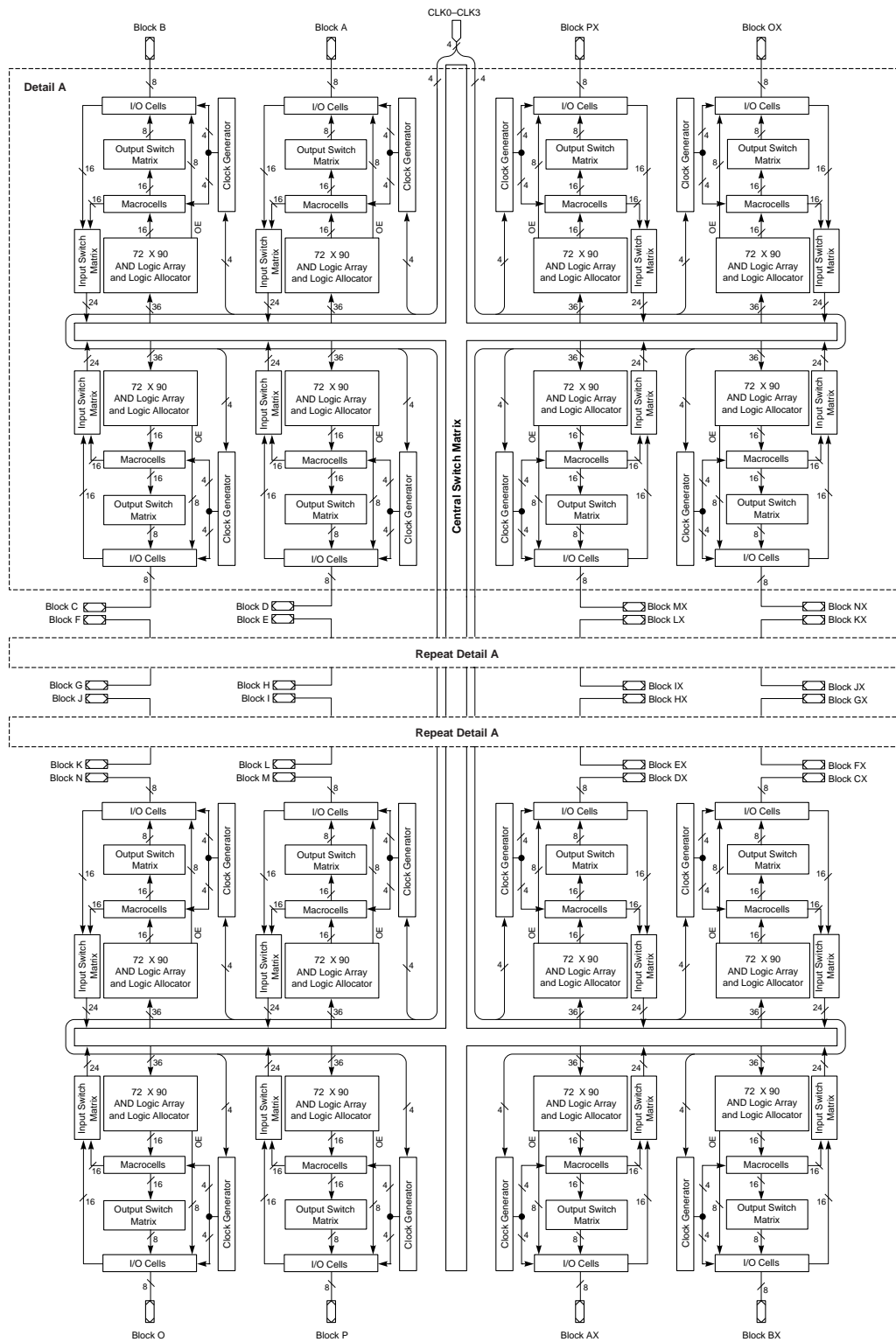
17466G-021

BLOCK DIAGRAM – M4A3-256/160, M4A3-256/192



17466G-050

BLOCK DIAGRAM - M4A3-512/160, M4A3-512/192, M4A3-512/256



17466G-068

ABSOLUTE MAXIMUM RATINGS

M4A5

Storage Temperature	-65°C to +150°C
Ambient Temperature with Power Applied	-55°C to +100°C
Device Junction Temperature	+130°C
Supply Voltage with Respect to Ground	-0.5 V to +7.0 V
DC Input Voltage	-0.5 V to $V_{CC} + 0.5$ V
Static Discharge Voltage	2000 V
Latchup Current ($T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$)	200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Ambient Temperature (T_A) Operating in Free Air	0°C to +70°C
Supply Voltage (V_{CC}) with Respect to Ground	+4.75 V to +5.25 V

Industrial (I) Devices

Ambient Temperature (T_A) Operating in Free Air	-40°C to +85°C
Supply Voltage (V_{CC}) with Respect to Ground	+4.50 V to +5.5 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

5-V DC CHARACTERISTICS OVER OPERATING RANGES

Parameter Symbol	Parameter Description	Test Conditions	Min	Typ	Max	Unit
V_{OH}	Output HIGH Voltage	$I_{OH} = -3.2$ mA, $V_{CC} = \text{Min}$, $V_{IN} = V_{IH}$ or V_{IL}	2.4			V
		$I_{OH} = -100$ μA , $V_{CC} = \text{Max}$, $V_{IN} = V_{IH}$ or V_{IL}		3.3	3.6	V
V_{OL}	Output LOW Voltage	$I_{OL} = 24$ mA, $V_{CC} = \text{Min}$, $V_{IN} = V_{IH}$ or V_{IL} (Note 1)			0.5	V
V_{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 2)	2.0			V
V_{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 2)			0.8	V
I_{IH}	Input HIGH Leakage Current	$V_{IN} = 5.25$ V, $V_{CC} = \text{Max}$ (Note 3)			10	μA
I_{IL}	Input LOW Leakage Current	$V_{IN} = 0$ V, $V_{CC} = \text{Max}$ (Note 3)			-10	μA
I_{OZH}	Off-State Output Leakage Current HIGH	$V_{OUT} = 5.25$ V, $V_{CC} = \text{Max}$, $V_{IN} = V_{IH}$ or V_{IL} (Note 3)			10	μA
I_{OZL}	Off-State Output Leakage Current LOW	$V_{OUT} = 0$ V, $V_{CC} = \text{Max}$, $V_{IN} = V_{IH}$ or V_{IL} (Note 3)			-10	μA
I_{SC}	Output Short-Circuit Current	$V_{OUT} = 0.5$ V, $V_{CC} = \text{Max}$ (Note 4)	-30		-160	mA

Notes:

- Total I_{OL} for one PAL block should not exceed 64 mA.
- These are absolute values with respect to device ground, and all overshoots due to system or tester noise are included.
- I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).
- Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second. $V_{OUT} = 0.5$ V has been chosen to avoid test problems caused by tester ground degradation.

I_{CC} vs. FREQUENCY

These curves represent the typical power consumption for a particular device at system frequency. The selected “typical” pattern is a 16-bit up-down counter. This pattern fills the device and exercises every macrocell. Maximum frequency shown uses internal feedback and a D-type register. Power/Speed are optimized to obtain the highest counter frequency and the lowest power. The highest frequency (LSBs) is placed in common PAL blocks, which are set to high power. The lowest frequency signals (MSBs) are placed in a common PAL block and set to lowest power.

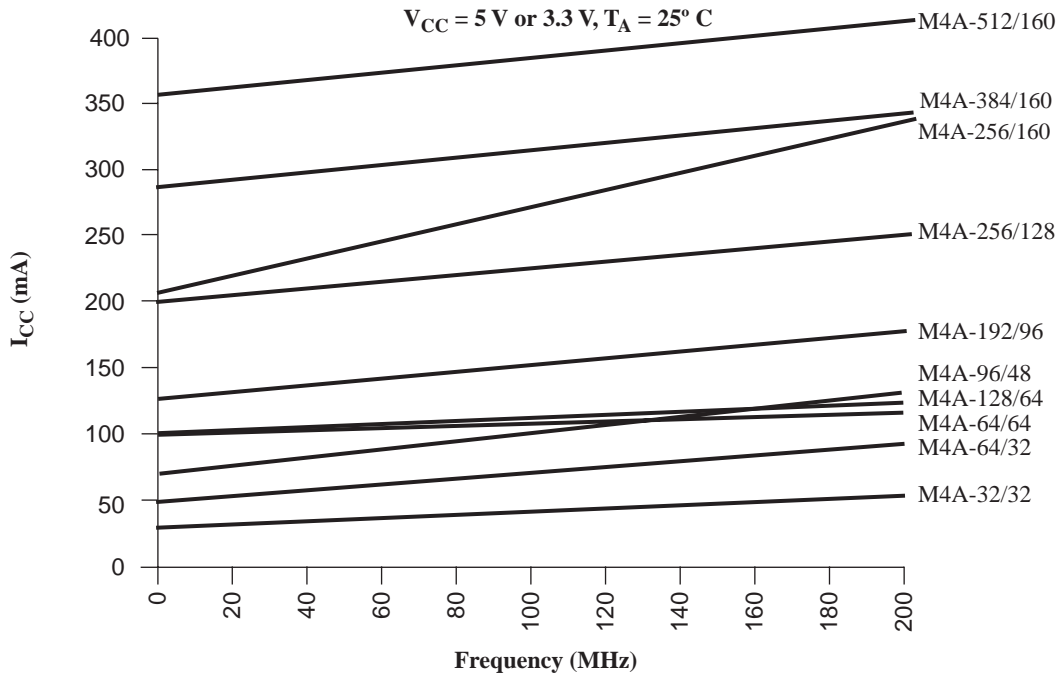


Figure 19. ispMACH 4A I_{CC} Curves at High Speed Mode

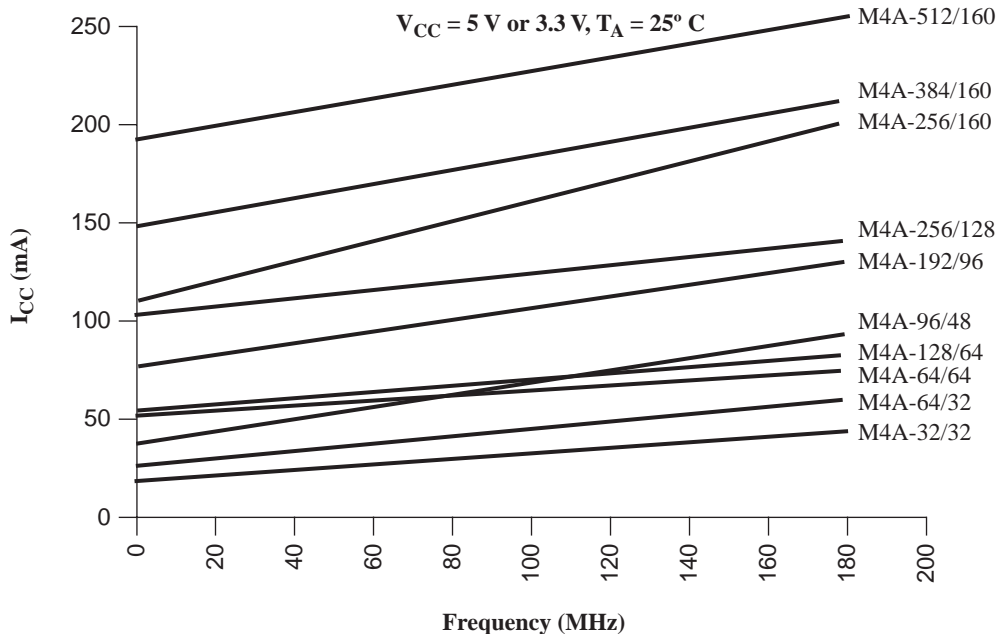


Figure 20. ispMACH 4A I_{CC} Curves at Low Power Mode

100-BALL caBGA CONNECTION DIAGRAM (M4A3-128/64)

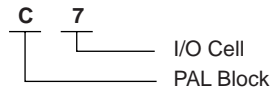
Bottom View

100-Ball caBGA

	10	9	8	7	6	5	4	3	2	1	
A	GND	I/O63 H7	I/O60 H4	I/O57 H1	GND	GND	I/O1 A1	I/O4 A4	I/O7 A7	GND	A
B	$\overline{\text{TRST}}$	GND	I/O61 H5	I5	VCC	I/O0 A0	I/O6 A6	GND	TDI	I/O15 B7	B
C	I/O53 G5	TDO	I/O62 H6	I/O58 H2	I/O56 H0	I/O2 A2	GND	I/O14 B6	I/O13 B5	I/O12 B4	C
D	I/O50 G2	I/O55 G7	GND	I/O59 H3	I/O3 A3	I/O5 A5	I/O11 B3	I/O10 B2	CLK0/I0	I/O9 B1	D
E	CLK3/I4	I/O49 G1	I/O51 G3	I/O54 G6	VCC	I/O16 C0	I/O20 C4	I/O8 B0	VCC	GND	E
F	GND	VCC	I/O40 F0	I/O52 G4	I/O48 G0	VCC	I/O22 C6	I/O19 C3	I/O17 C1	CLK1/I1	F
G	I/O41 F1	CLK2/I3	I/O42 F2	I/O43 F3	I/O37 E5	I/O35 E3	I/O27 D3	GND	I/O23 C7	I/O18 C2	G
H	I/O44 F4	I/O45 F5	I/O46 F6	GND	I/O34 E2	I/O24 D0	I/O26 D2	I/O30 D6	TCK	I/O21 C5	H
J	I/O47 F7	$\overline{\text{ENABLE}}$	GND	I/O38 E6	I/O32 E0	VCC	I2	I/O29 D5	GND	TMS	J
K	GND	I/O39 E7	I/O36 E4	I/O33 E1	GND	GND	I/O25 D1	I/O28 D4	I/O31 D7	GND	K

PIN DESIGNATIONS

CLK = Clock
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 N/C = No Connect
 VCC = Supply Voltage
 TDI = Test Data In
 TCK = Test Clock
 TMS = Test Mode Select
 TDO = Test Data Out
 $\overline{\text{TRST}}$ = Test Reset
 ENABLE = Program



17466G-100cabga

144-BALL FPBGA CONNECTION DIAGRAM (M4A3-192/96)

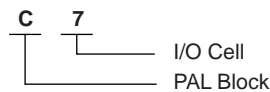
Bottom View

144-Ball fpBGA

	12	11	10	9	8	7	6	5	4	3	2	1	
A	GND	I/O72 L7	I/O76 L3	I13	GBCLK3	I0	I/O82 A2	I/O86 A6	I/O88 B0	I/O93 B5	I/O95 B7	GND	A
B	GND	I/O73 L6	I/O77 L2	I/O79 L0	VCC	I1	I/O83 A3	I/O87 A7	I/O90 B2	I/O94 B6	I/O0 D7	TDI	B
C	GND	TD0	I/O74 L5	I14	GND	I/O80 A0	I/O84 A4	GND	I/O92 B4	I/O1 D6	I/O4 D3	I/O3 D4	C
D	I/O67 K4	I/O69 K2	I/O71 K0	I/O75 L4	GBCLK0	I/O81 A1	VCC	I/O91 B3	I/O2 D5	I2	I/O6 D1	I/O7 D0	D
E	I12	I/O64 K7	I/O66 K5	I/O70 K1	I/O78 L1	I/O85 A5	I/O89 B1	I/O5 D2	I/O8 C7	I4	GND	VCC	E
F	I10	I11	GND	I/O65 K6	I/O68 K3	I15	I3	GND	I/O12 C3	I/O11 C4	I/O10 C5	I/O9 C6	F
G	I/O60 J3	I/O61 J2	I/O62 J1	I/O63 J0	VCC	GND	I7	I/O20 E3	I/O17 E6	I/O15 C0	I/O14 C1	I/O13 C2	G
H	I/O56 J7	I/O57 J6	I/O58 J5	I/O59 J4	I/O53 I2	I/O41 H1	I/O37 G5	I/O30 F1	I/O22 E1	I/O18 E5	I/O16 E7	VCC	H
J	I/O55 I0	I/O54 I1	VCC	I/O50 I5	I/O43 H3	VCC	I/O33 G1	GBCLK2	I/O27 F4	I/O23 E0	I/O21 E2	I/O19 E4	J
K	I/O51 I4	I/O52 I3	I/O49 I6	I/O44 H4	GND	I/O36 G4	I/O32 G0	VCC	I6	I/O26 F5	TCK	TMS	K
L	GND	I/O48 I7	I/O46 H6	I/O42 H2	I/O39 G7	I/O35 G3	I9	GND	I/O31 F0	I/O29 F2	I/O25 F6	GND	L
M	GND	I/O47 H7	I/O45 H5	I/O40 H0	I/O38 G6	I/O34 G2	I8	GBCLK1	I5	I/O28 F3	I/O24 F7	GND	M
	12	11	10	9	8	7	6	5	4	3	2	1	

PIN DESIGNATIONS

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- VCC = Supply Voltage
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- TCK = Test Clock
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- TD0 = Test Data Out



388-BALL fpBGA CONNECTION DIAGRAM (M4A3-512/256)

Bottom View

388-Ball fpBGA

	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
A	GND	I/O243 OX3	I/O240 OX0	I/O241 OX1	I/O236 NX4	I/O231 MX7	I/O228 MX4	I/O226 MX2	I/O255 PX7	I/O251 PX3	I/O248 PX0	I/O0 A0	I/O5 A5	I/O6 A6	I/O27 D3	I/O30 D6	I/O17 C1	I/O22 C6	I/O8 B0	I/O10 B2	N/C	GND	A
B	N/C	GND	I/O245 OX5	I/O242 OX2	I/O238 NX6	I/O234 NX2	I/O232 NX0	I/O229 MX5	I/O224 MX0	I/O253 PX5	I/O249 PX1	I/O2 A2	CLK0	I/O26 D2	I/O29 D5	I/O31 D7	I/O20 C4	I/O9 B1	I/O12 B4	I/O13 B5	GND	TDI	B
C	I/O213 KX5	TDO	GND	I/O247 OX7	I/O244 OX4	I/O239 NX7	I/O235 NX3	I/O230 MX6	I/O227 MX3	CLK3	I/O250 PX2	I/O1 A1	I/O7 A7	I/O25 D1	I/O16 C0	I/O18 C2	I/O23 C7	I/O11 B3	I/O15 B7	GND	I/O47 F7	I/O44 F4	C
D	I/O210 KX2	I/O212 KX4	I/O215 KX7	GND	I/O246 OX6	VCC	I/O237 NX5	I/O233 NX1	VCC	I/O254 PX6	VCC	I/O3 A3	I/O24 D0	VCC	I/O19 C3	I/O21 C5	VCC	I/O14 B6	GND	I/O46 F6	I/O43 F3	I/O41 F1	D
E	I/O207 JX7	I/O209 KX1	I/O211 KX3	I/O214 KX6															I/O45 F5	I/O42 F2	I/O40 F0	I/O54 G6	E
F	I/O203 JX3	I/O205 JX5	I/O208 KX0	VCC															VCC	I/O55 G7	I/O52 G4	I/O50 G2	F
G	I/O200 JX0	I/O202 JX2	I/O204 JX4	I/O206 JX6			VCC	VCC	N/C	I/O225 MX1	I/O252 PX4	I/O4 A4	I/O28 D4	N/C	VCC	VCC			I/O53 G5	I/O51 G3	I/O49 G1	I/O39 E7	G
H	I/O221 LX5	I/O222 LX6	I/O223 LX7	I/O201 JX1			VCC	N/C	GND	GND	GND	GND	GND	GND	N/C	VCC			I/O48 G0	I/O38 E6	I/O37 E5	I/O36 E4	H
J	I/O218 LX2	I/O219 LX3	I/O220 LX4	VCC			N/C	GND	GND	GND	GND	GND	GND	GND	GND	N/C			VCC	I/O35 E3	I/O34 E2	I/O32 E0	J
K	I/O197 IX5	I/O198 IX6	I/O199 IX7	I/O216 LX0			I/O217 LX1	GND	GND	GND	GND	GND	GND	GND	GND	I/O33 E1			I/O63 H7	I/O62 H6	I/O61 H5	I/O60 H4	K
L	I/O192 IX0	I/O194 IX2	I/O195 IX3	I/O196 IX4			I/O193 IX1	GND	GND	GND	GND	GND	GND	GND	GND	I/O58 H2			VCC	I/O59 H3	I/O57 H1	I/O56 H0	L
M	I/O184 HX0	I/O185 HX1	I/O187 HX3	VCC			I/O186 HX2	GND	GND	GND	GND	GND	GND	GND	GND	I/O69 I5			I/O67 I3	I/O65 I1	I/O66 I2	I/O64 I0	M
N	I/O188 HX4	I/O189 HX5	I/O191 HX7	I/O190 HX6			I/O182 EX2	GND	GND	GND	GND	GND	GND	GND	GND	I/O89 L1			I/O88 L0	I/O71 I7	I/O70 I6	I/O68 I4	N
P	I/O160 EX0	I/O161 EX1	I/O163 EX3	VCC			N/C	GND	GND	GND	GND	GND	GND	GND	GND	N/C			VCC	I/O92 L4	I/O91 L3	I/O90 L2	P
R	I/O164 EX4	I/O165 EX5	I/O166 EX6	I/O177 GX1			VCC	N/C	GND	GND	GND	GND	GND	GND	N/C	VCC			I/O74 J2	I/O95 L7	I/O94 L6	I/O93 L5	R
T	I/O167 EX7	I/O176 GX0	I/O179 GX3	I/O181 GX5			VCC	VCC	N/C	I/O152 DX0	I/O131 AX3	I/O122 P2	I/O98 M2	N/C	VCC	VCC			I/O78 J6	I/O76 J4	I/O73 J1	I/O72 J0	T
U	I/O178 GX2	I/O180 GX4	I/O183 GX7	VCC															VCC	I/O80 K0	I/O77 J5	I/O75 J3	U
V	I/O182 GX6	N/C	I/O169 FX1	I/O172 FX4															I/O86 K6	I/O83 K3	I/O81 K1	I/O79 J7	V
W	I/O168 FX0	I/O170 FX2	I/O173 FX5	GND	I/O143 BX7	VCC	I/O150 CX6	I/O145 CX1	VCC	I/O153 DX1	I/O123 P3	VCC	I/O96 M0	VCC	I/O104 N0	I/O111 N7	VCC	I/O119 O7	GND	I/O87 K7	I/O84 K4	I/O82 K2	W
Y	I/O171 FX3	I/O174 FX6	GND	I/O141 BX5	I/O138 BX2	I/O136 BX0	I/O147 CX3	I/O158 DX6	I/O156 DX4	CLK2	I/O132 AX4	I/O121 P1	I/O125 P5	I/O99 M3	I/O101 M5	I/O106 N2	I/O110 N6	I/O115 O3	I/O118 O6	GND	TMS	I/O85 K5	Y
AA	I/O175 FX7	GND	I/O142 BX6	I/O140 BX4	I/O151 CX7	I/O149 CX5	I/O144 CX0	I/O157 DX5	I/O154 DX2	I/O134 AX6	I/O130 AX2	I/O128 AX0	CLK1	I/O127 P7	I/O100 M4	I/O103 M7	I/O108 N4	I/O109 N5	I/O113 O1	I/O116 O4	GND	TCK	AA
AB	GND	N/C	I/O139 BX3	I/O137 BX1	I/O148 CX4	I/O146 CX2	I/O159 DX7	I/O155 DX3	I/O135 AX7	I/O133 AX5	I/O129 AX1	I/O120 P0	I/O124 P4	I/O126 P6	I/O97 M1	I/O102 M6	I/O105 N1	I/O107 N3	I/O112 O0	I/O114 O2	I/O117 O5	GND	AB

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m4a3.512.256_388bga

Revision History

Date	Version	Change Summary
-	K	Previous Lattice release.
August 2006	L	Updated for lead-free package options.
September 2006	M	Revised M4A3-256/160 208-pin PQFP connection diagram.